



Material Content Data Sheet



Sales Product Name		BCR602		Issued		9. January 2019		
MA#		MA002805580						
Package		PG-SOT23-6-3		Weight*		18.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.404	2.18	2.18	21819	21819
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		118	
	non noble metal	zinc	7440-66-6	0.009	0.05		472	
	non noble metal	iron	7439-89-6	0.175	0.94		9430	
wires	non noble metal	copper	7440-50-8	7.097	38.29	39.29	382890	392910
	noble metal	palladium	7440-05-3	0.000	0.00		22	
	non noble metal	copper	7440-50-8	0.040	0.22	0.22	2172	2194
encapsulation	organic material	carbon black	1333-86-4	0.020	0.11		1068	
	plastics	epoxy resin	-	1.514	8.17		81710	
	inorganic material	silicondioxide	60676-86-0	8.364	45.13	53.41	451272	534050
leadfinish	non noble metal	tin	7440-31-5	0.465	2.51	2.51	25077	25077
plating	noble metal	silver	7440-22-4	0.175	0.94	0.94	9422	9422
glue	plastics	acrylic resin	-	0.059	0.32		3196	
	noble metal	silver	7440-22-4	0.210	1.13	1.45	11332	14528
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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